

ZXMN6A11G

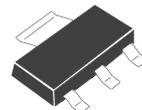
60V N-CANNEL ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS}=60V$; $R_{DS(ON)}=0.15\Omega$ $I_D=3.8A$

DESCRIPTION

This new generation of TRENCH MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



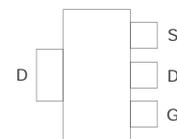
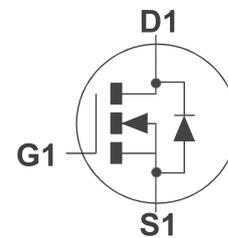
SOT223

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- Low profile SOIC package

APPLICATIONS

- DC - DC Converters
- Power Management Functions
- Disconnect switches
- Motor control



Top View

ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMN6A11GTA	7"	12mm	1000 units
ZXMN6A11GTC	13"	12mm	4000 units

DEVICE MARKING

- ZXMN
6A11

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ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	60	V
Gate Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($V_{GS}=10V$; $T_A=25^\circ C$)(b) ($V_{GS}=10V$; $T_A=70^\circ C$)(b) ($V_{GS}=10V$; $T_A=25^\circ C$)(a)	I_D	3.8 3.0 2.7	A
Pulsed Drain Current (c)	I_{DM}	10	A
Continuous Source Current (Body Diode) (b)	I_S	5.0	A
Pulsed Source Current (Body Diode)(c)	I_{SM}	10	A
Power Dissipation at $T_A=25^\circ C$ (a) Linear Derating Factor	P_D	2.0 16	W mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ (b) Linear Derating Factor	P_D	3.9 31	W mW/ $^\circ C$
Operating and Storage Temperature Range	$T_J; T_{stg}$	-55 to +150	$^\circ C$

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	62.5	$^\circ C/W$
Junction to Ambient (b)	$R_{\theta JA}$	32	$^\circ C/W$

NOTES

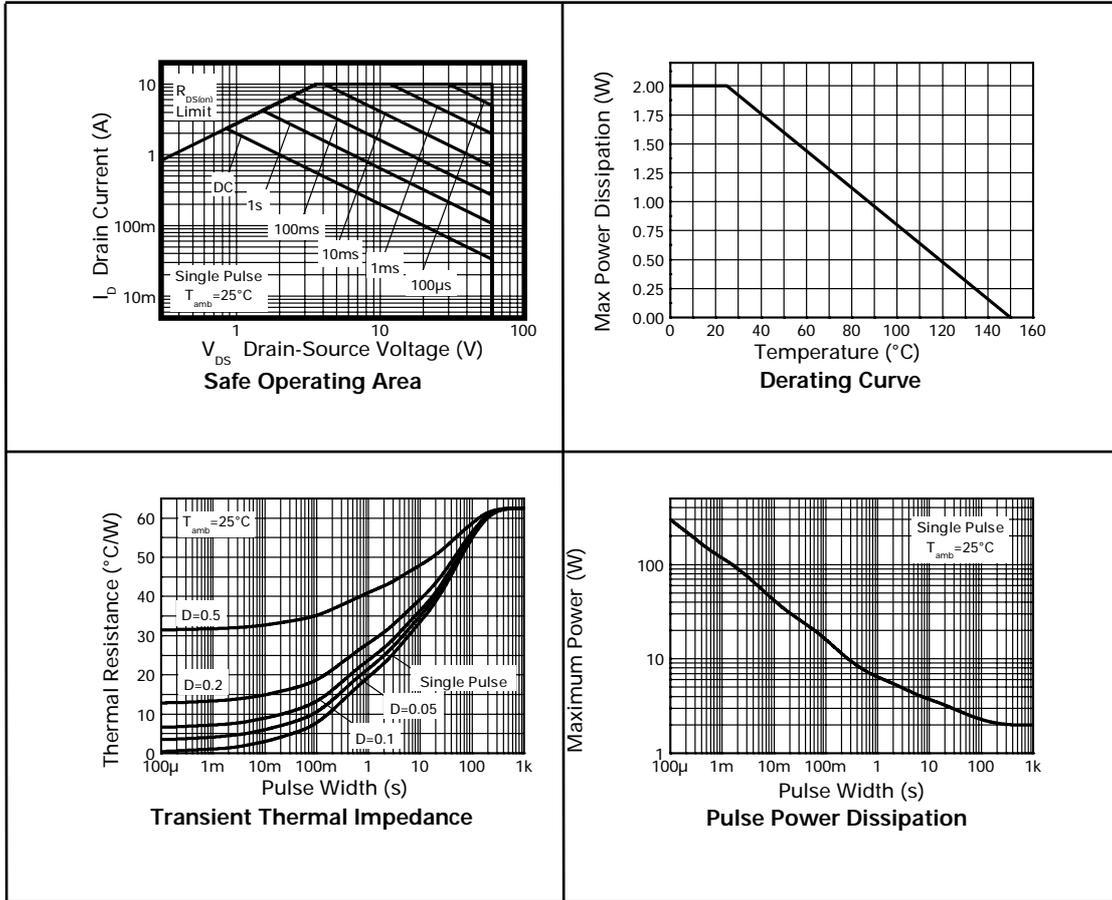
(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at $t \leq 10$ secs.

(c) Repetitive rating 25mm x 25mm FR4 PCB, $D=0.05$ pulse width=10 μs - pulse width limited by maximum junction temperature.



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ELECTRICAL CHARACTERISTICS (at $T_A = 25^\circ\text{C}$ unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	60			V	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}			1	μA	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$
Gate-Body Leakage	I_{GSS}			100	nA	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	1.0			V	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.150 0.250	Ω	$V_{GS}=10\text{V}, I_D=4.4\text{A}$ $V_{GS}=4.5\text{V}, I_D=3.8\text{A}$
Forward Transconductance (3)	g_{fs}		4.9		S	$V_{DS}=15\text{V}, I_D=2.5\text{A}$
DYNAMIC (3)						
Input Capacitance	C_{iss}		330		pF	$V_{DS}=40\text{V}, V_{GS}=0\text{V},$ $f=1\text{MHz}$
Output Capacitance	C_{oss}		35.2		pF	
Reverse Transfer Capacitance	C_{rss}		17.1		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	$t_{d(on)}$		1.95		ns	$V_{DD}=30\text{V}, I_D=2.5\text{A}$ $R_G=6.0\Omega, V_{GS}=10\text{V}$ (refer to test circuit)
Rise Time	t_r		3.5		ns	
Turn-Off Delay Time	$t_{d(off)}$		8.2		ns	
Fall Time	t_f		4.6		ns	
Gate Charge	Q_g		3.0		nC	$V_{DS}=15\text{V}, V_{GS}=5\text{V},$ $I_D=2.5\text{A}$
Total Gate Charge	Q_g		5.7		nC	$V_{DS}=15\text{V}, V_{GS}=10\text{V},$ $I_D=2.5\text{A}$ (refer to test circuit)
Gate-Source Charge	Q_{gs}		1.25		nC	
Gate-Drain Charge	Q_{gd}		0.86		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}		0.85	0.95	V	$T_j=25^\circ\text{C}, I_s=2.8\text{A},$ $V_{GS}=0\text{V}$
Reverse Recovery Time (3)	t_{rr}		21.5		ns	$T_j=25^\circ\text{C}, I_r=2.5\text{A},$ $di/dt=100\text{A}/\mu\text{s}$
Reverse Recovery Charge (3)	Q_{rr}		20.5		nC	

NOTES

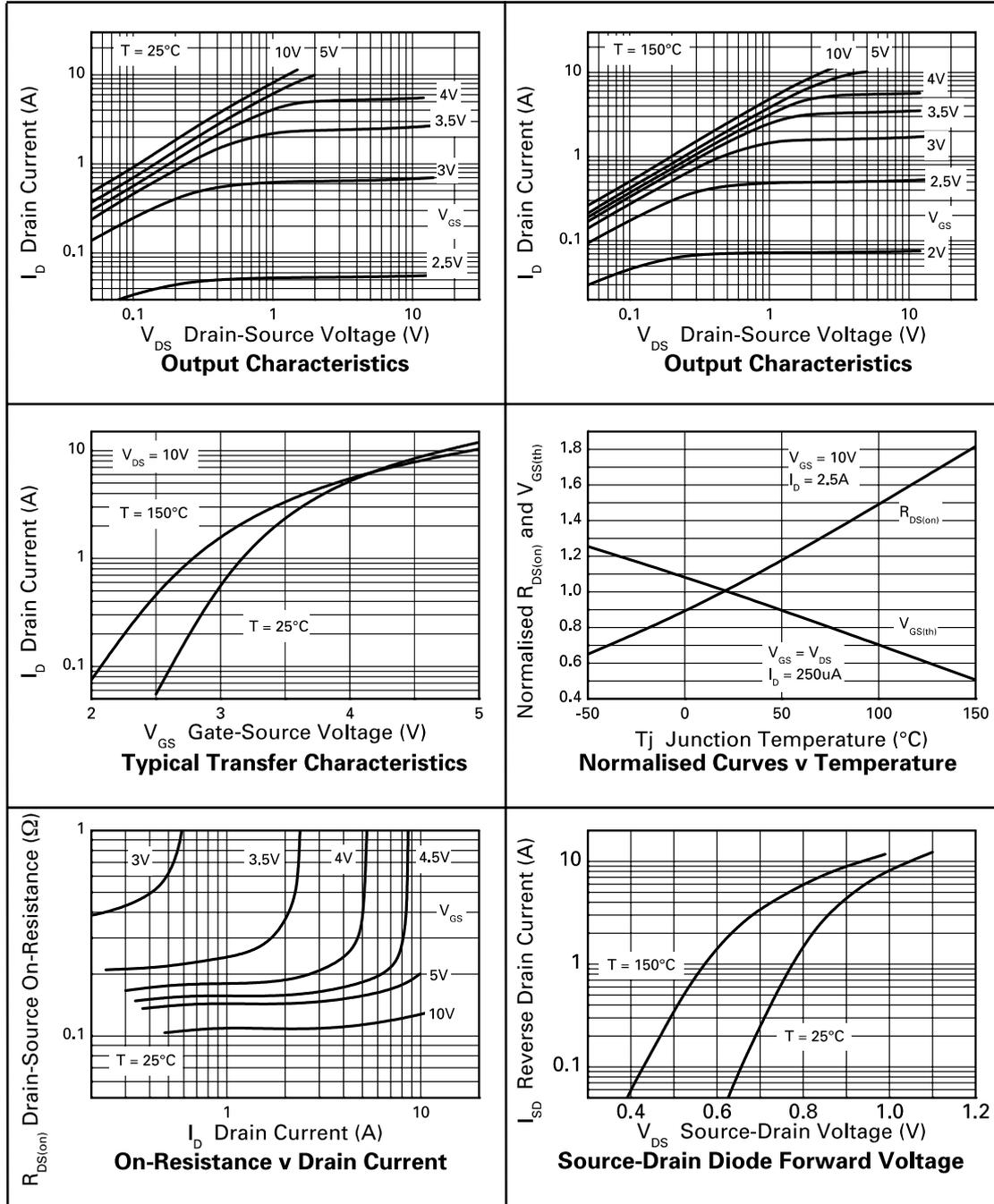
- (1) Measured under pulsed conditions. Width=300 μs . Duty cycle $\leq 2\%$.
 (2) Switching characteristics are independent of operating junction temperature.
 (3) For design aid only, not subject to production testing.



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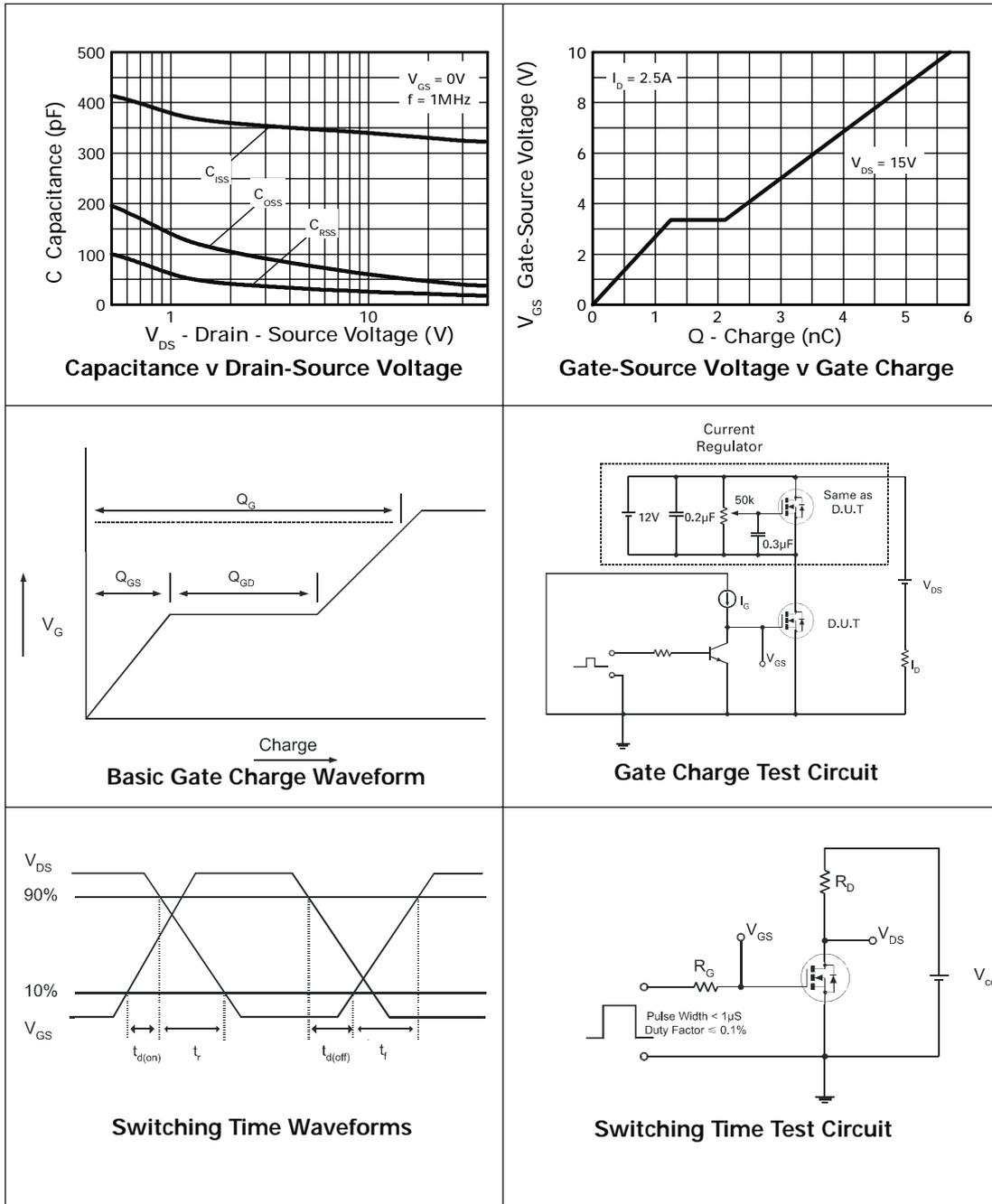
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TYPICAL CHARACTERISTICS



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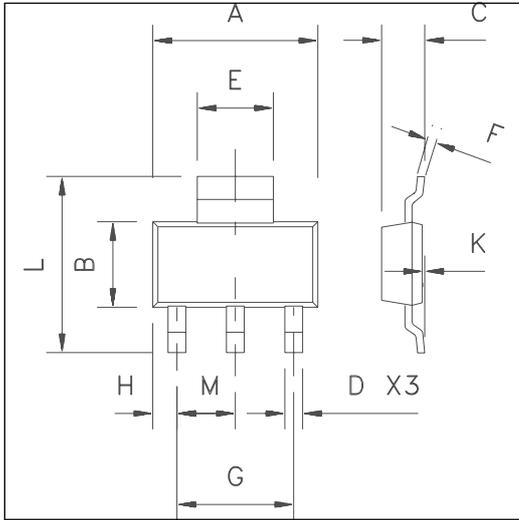
TYPICAL CHARACTERISTICS



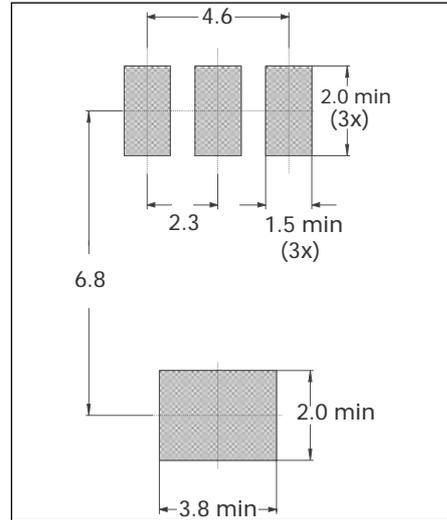
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PACKAGE DIMENSIONS



PAD LAYOUT DETAILS



DIM	Millimetres		Inches	
	Min	Max	Min	Max
A	6.3	6.7	0.248	0.264
B	3.3	3.7	0.130	0.146
C	-	1.7	-	0.067
D	0.6	0.8	0.024	0.031
E	2.9	3.1	0.114	0.122
F	0.24	0.32	0.009	0.13
G	NMO 4.6		NOM 0.181	
H	0.85	1.05	0.033	0.041
K	0.02	0.10	0.0008	0.004
L	6.7	7.3	0.264	0.287
M	NOM 2.3		NOM 0.0905	



ZETEX

Zetex plc.
Fields New Road, Chadderton, Oldham, OL9-8NP, United Kingdom.
Telephone: (44)161 622 4422 (Sales), (44)161 622 4444 (General Enquiries)
Fax: (44)161 622 4420

Zetex GmbH
Streitfeldstraße 19
D-81673 München
Germany
Telephone: (49) 89 45 49 49 0
Fax: (49) 89 45 49 49 49

Zetex Inc.
Suite 315
700 Veterans Memorial Highway
USA
Telephone: (631) 360-2222
Fax: (631) 360-8222

Zetex (Asia) Ltd.
3701-04 Metroplaza, Tower 1
Hing Fong Road,
Kwai Fong, Hong Kong
Telephone: (852) 26100 611
Fax: (852) 24250 494

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